



#8/16/03

Docket No.: M1071.1453/P1453
(PATENT)

7/3/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Haruhiko Ikeda

Application No.: 09/927,053

Group Art Unit: 1733

Filed: August 9, 2001

Examiner: John T. Haran

For: METHOD OF BONDING A
CONDUCTIVE ADHESIVE AND AN
ELECTRODE, AND A BONDED
ELECTRODE OBTAINED THEREBY

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TC 1700

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Restriction Requirement set forth in the Office Action mailed June 5, 2003, Applicant hereby provisionally elects claims 19-27, drawn to a bonded structure, for continued examination, without traverse.

Applicant reserves the right to file one or more divisional applications directed to the subject matter of the non-elected claims.

Consideration and allowance of the application is respectfully solicited.

Dated: June 30, 2003

Respectfully submitted,

By

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